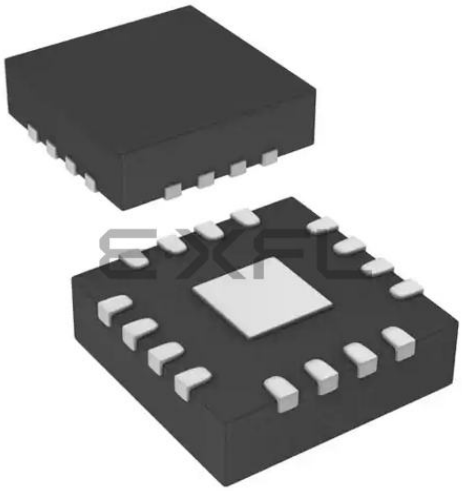

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	11
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-VFQFN Exposed Pad
Supplier Device Package	16-QFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1503t-i-mg

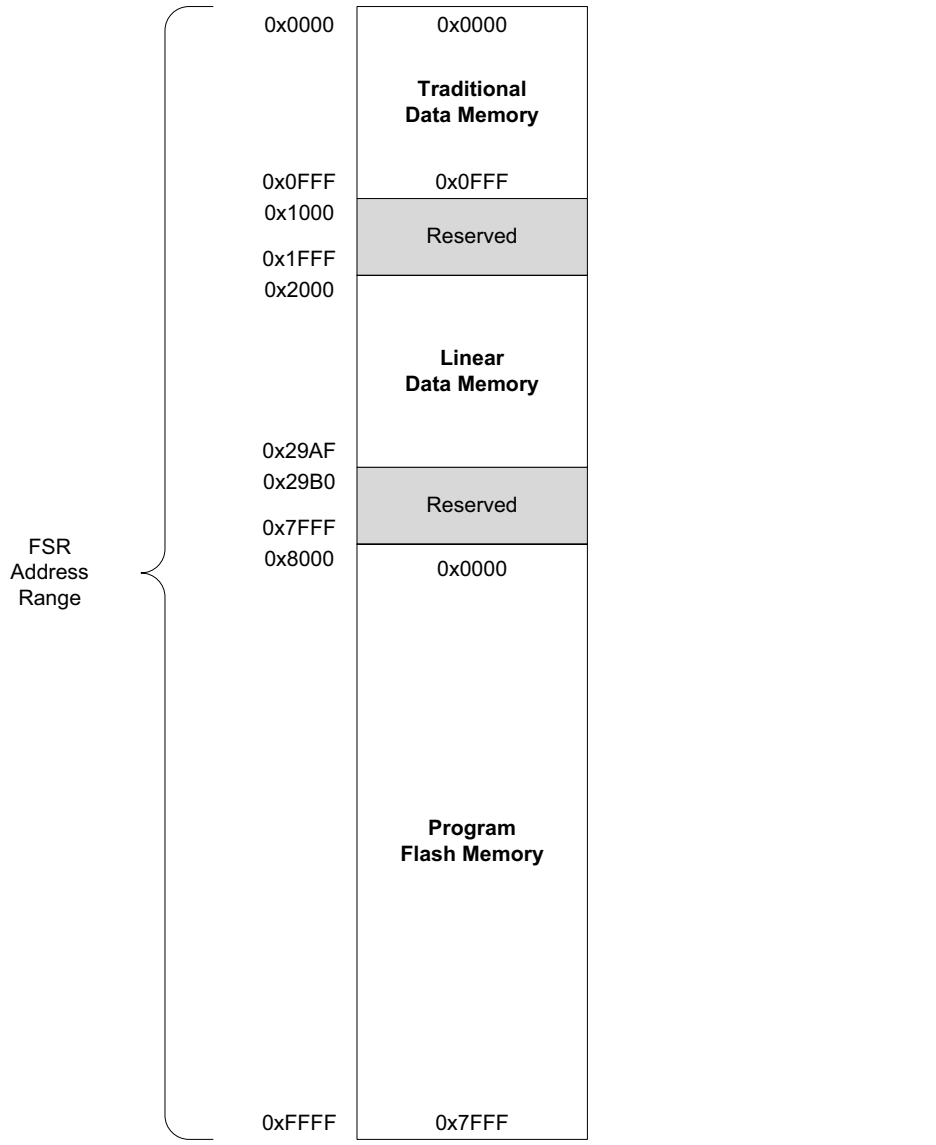
TABLE 3-3: PIC16(L)F1503 MEMORY MAP (CONTINUED)

BANK 8		BANK 9		BANK 10		BANK 11		BANK 12		BANK 13		BANK 14		BANK 15	
400h	Core Registers (Table 3-2)	480h	Core Registers (Table 3-2)	500h	Core Registers (Table 3-2)	580h	Core Registers (Table 3-2)	600h	Core Registers (Table 3-2)	680h	Core Registers (Table 3-2)	700h	Core Registers (Table 3-2)	780h	Core Registers (Table 3-2)
40Bh		48Bh		50Bh		58Bh		60Bh		68Bh		70Bh		78Bh	
40Ch	—	48Ch	—	50Ch	—	58Ch	—	60Ch	—	68Ch	—	70Ch	—	78Ch	—
40Dh	—	48Dh	—	50Dh	—	58Dh	—	60Dh	—	68Dh	—	70Dh	—	78Dh	—
40Eh	—	48Eh	—	50Eh	—	58Eh	—	60Eh	—	68Eh	—	70Eh	—	78Eh	—
40Fh	—	48Fh	—	50Fh	—	58Fh	—	60Fh	—	68Fh	—	70Fh	—	78Fh	—
410h	—	490h	—	510h	—	590h	—	610h	—	690h	—	710h	—	790h	—
411h	—	491h	—	511h	—	591h	—	611h	PWM1DCL	691h	CWG1DBR	711h	—	791h	—
412h	—	492h	—	512h	—	592h	—	612h	PWM1DCH	692h	CWG1DBF	712h	—	792h	—
413h	—	493h	—	513h	—	593h	—	613h	PWM1CON	693h	CWG1CON0	713h	—	793h	—
414h	—	494h	—	514h	—	594h	—	614h	PWM2DCL	694h	CWG1CON1	714h	—	794h	—
415h	—	495h	—	515h	—	595h	—	615h	PWM2DCH	695h	CWG1CON2	715h	—	795h	—
416h	—	496h	—	516h	—	596h	—	616h	PWM2CON	696h	—	716h	—	796h	—
417h	—	497h	—	517h	—	597h	—	617h	PWM3DCL	697h	—	717h	—	797h	—
418h	—	498h	NCO1ACCL	518h	—	598h	—	618h	PWM3DCH	698h	—	718h	—	798h	—
419h	—	499h	NCO1ACCH	519h	—	599h	—	619h	PWM3CON	699h	—	719h	—	799h	—
41Ah	—	49Ah	NCO1ACCU	51Ah	—	59Ah	—	61Ah	PWM4DCL	69Ah	—	71Ah	—	79Ah	—
41Bh	—	49Bh	NCO1INCL	51Bh	—	59Bh	—	61Bh	PWM4DCH	69Bh	—	71Bh	—	79Bh	—
41Ch	—	49Ch	NCO1INCH	51Ch	—	59Ch	—	61Ch	PWM4CON	69Ch	—	71Ch	—	79Ch	—
41Dh	—	49Dh	—	51Dh	—	59Dh	—	61Dh	—	69Dh	—	71Dh	—	79Dh	—
41Eh	—	49Eh	NCO1CON	51Eh	—	59Eh	—	61Eh	—	69Eh	—	71Eh	—	79Eh	—
41Fh	—	49Fh	NCO1CLK	51Fh	—	59Fh	—	61Fh	—	69Fh	—	71Fh	—	79Fh	—
420h	Unimplemented Read as '0'	4A0h	Unimplemented Read as '0'	520h	Unimplemented Read as '0'	5A0h	Unimplemented Read as '0'	620h	Unimplemented Read as '0'	6A0h	Unimplemented Read as '0'	720h	Unimplemented Read as '0'	7A0h	Unimplemented Read as '0'
46Fh		4EFh		56Fh		5EFh		66Fh		6EFh		76Fh		7EFh	
470h	Common RAM (Accesses 70h – 7Fh)	4F0h	Common RAM (Accesses 70h – 7Fh)	570h	Common RAM (Accesses 70h – 7Fh)	5F0h	Common RAM (Accesses 70h – 7Fh)	670h	Common RAM (Accesses 70h – 7Fh)	6F0h	Common RAM (Accesses 70h – 7Fh)	770h	Common RAM (Accesses 70h – 7Fh)	7F0h	Common RAM (Accesses 70h – 7Fh)
47Fh		4FFh		57Fh		5FFh		67Fh		6FFh		77Fh		7FFh	

BANK 16		BANK 17		BANK 18		BANK 19		BANK 20		BANK 21		BANK 22		BANK 23	
800h	Core Registers (Table 3-2)	880h	Core Registers (Table 3-2)	900h	Core Registers (Table 3-2)	980h	Core Registers (Table 3-2)	A00h	Core Registers (Table 3-2)	A80h	Core Registers (Table 3-2)	B00h	Core Registers (Table 3-2)	B80h	Core Registers (Table 3-2)
80Bh		88Bh		90Bh		98Bh		A0Bh		A8Bh		B0Bh		B8Bh	
80Ch	Unimplemented Read as '0'	88Ch	Unimplemented Read as '0'	90Ch	Unimplemented Read as '0'	98Ch	Unimplemented Read as '0'	A0Ch	Unimplemented Read as '0'	A8Ch	Unimplemented Read as '0'	B0Ch	Unimplemented Read as '0'	B8Ch	Unimplemented Read as '0'
86Fh		8EFh		96Fh		9EFh		A6Fh		AEFh		B6Fh		BEFh	
870h	Common RAM (Accesses 70h – 7Fh)	8F0h	Common RAM (Accesses 70h – 7Fh)	970h	Common RAM (Accesses 70h – 7Fh)	9F0h	Common RAM (Accesses 70h – 7Fh)	A70h	Common RAM (Accesses 70h – 7Fh)	AF0h	Common RAM (Accesses 70h – 7Fh)	B70h	Common RAM (Accesses 70h – 7Fh)	BF0h	Common RAM (Accesses 70h – 7Fh)
87Fh		8FFh		97Fh		9FFh		A7Fh		AFFh		B7Fh		BFFh	

Legend: = Unimplemented data memory locations, read as '0'

FIGURE 3-8: INDIRECT ADDRESSING



Note: Not all memory regions are completely implemented. Consult device memory tables for memory limits.

6.1 Power-On Reset (POR)

The POR circuit holds the device in Reset until VDD has reached an acceptable level for minimum operation. Slow rising VDD, fast operating speeds or analog performance may require greater than minimum VDD. The PWRT, BOR or MCLR features can be used to extend the start-up period until all device operation conditions have been met.

6.1.1 POWER-UP TIMER (PWRT)

The Power-up Timer provides a nominal 64 ms time-out on POR or Brown-out Reset.

The device is held in Reset as long as PWRT is active. The PWRT delay allows additional time for the VDD to rise to an acceptable level. The Power-up Timer is enabled by clearing the PWRTE bit in Configuration Words.

The Power-up Timer starts after the release of the POR and BOR.

For additional information, refer to Application Note AN607, *"Power-up Trouble Shooting"* (DS00607).

6.2 Brown-Out Reset (BOR)

The BOR circuit holds the device in Reset when VDD reaches a selectable minimum level. Between the POR and BOR, complete voltage range coverage for execution protection can be implemented.

The Brown-out Reset module has four operating modes controlled by the BOREN<1:0> bits in Configuration Words. The four operating modes are:

- BOR is always on
- BOR is off when in Sleep
- BOR is controlled by software
- BOR is always off

Refer to Table 6-1 for more information.

The Brown-out Reset voltage level is selectable by configuring the BORV bit in Configuration Words.

A VDD noise rejection filter prevents the BOR from triggering on small events. If VDD falls below Vpor for a duration greater than parameter TBORDC, the device will reset. See Figure 6-2 for more information.

TABLE 6-1: BOR OPERATING MODES

BOREN<1:0>	SBOREN	Device Mode	BOR Mode	Instruction Execution upon: Release of POR or Wake-up from Sleep
11	X	X	Active	Waits for BOR ready(1) (BORRDY = 1)
10	X	Awake	Active	Waits for BOR ready (BORRDY = 1)
		Sleep	Disabled	
01	1	X	Active	Waits for BOR ready(1) (BORRDY = 1)
	0	X	Disabled	Begins immediately (BORRDY = x)
00	X	X	Disabled	

Note 1: In these specific cases, "release of POR" and "wake-up from Sleep," there is no delay in start-up. The BOR ready flag, (BORRDY = 1), will be set before the CPU is ready to execute instructions because the BOR circuit is forced on by the BOREN<1:0> bits.

6.2.1 BOR IS ALWAYS ON

When the BOREN bits of Configuration Words are programmed to '11', the BOR is always on. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is active during Sleep. The BOR does not delay wake-up from Sleep.

6.2.2 BOR IS OFF IN SLEEP

When the BOREN bits of Configuration Words are programmed to '10', the BOR is on, except in Sleep. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is not active during Sleep. The device wake-up will be delayed until the BOR is ready.

6.2.3 BOR CONTROLLED BY SOFTWARE

When the BOREN bits of Configuration Words are programmed to '01', the BOR is controlled by the SBOREN bit of the BORCON register. The device start-up is not delayed by the BOR ready condition or the VDD level.

BOR protection begins as soon as the BOR circuit is ready. The status of the BOR circuit is reflected in the BORRDY bit of the BORCON register.

BOR protection is unchanged by Sleep.

10.2.1 READING THE FLASH PROGRAM MEMORY

To read a program memory location, the user must:

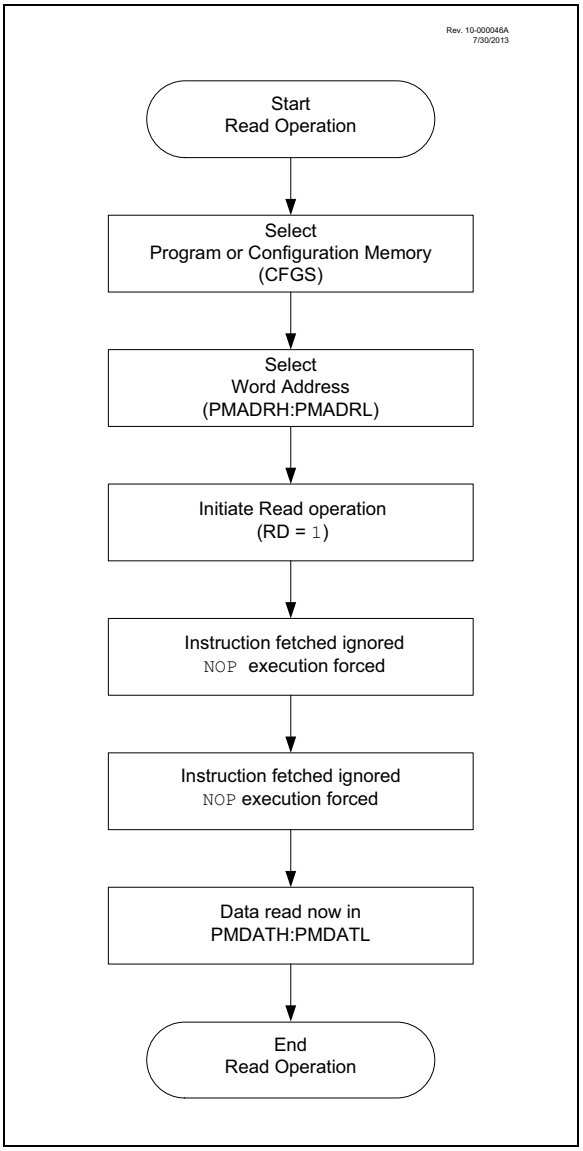
1. Write the desired address to the PMADRH:PMADRL register pair.
2. Clear the CFGS bit of the PMCON1 register.
3. Then, set control bit RD of the PMCON1 register.

Once the read control bit is set, the program memory Flash controller will use the second instruction cycle to read the data. This causes the second instruction immediately following the "BSF PMCON1,RD" instruction to be ignored. The data is available in the very next cycle, in the PMDATH:PMDATL register pair; therefore, it can be read as two bytes in the following instructions.

PMDATH:PMDATL register pair will hold this value until another read or until it is written to by the user.

Note:	The two instructions following a program memory read are required to be NOPs. This prevents the user from executing a 2-cycle instruction on the next instruction after the RD bit is set.

FIGURE 10-1: FLASH PROGRAM MEMORY READ FLOWCHART



11.0 I/O PORTS

Each port has three standard registers for its operation. These registers are:

- TRISx registers (data direction)
- PORTx registers (reads the levels on the pins of the device)
- LATx registers (output latch)

Some ports may have one or more of the following additional registers. These registers are:

- ANSELx (analog select)
- WPUx (weak pull-up)

In general, when a peripheral is enabled on a port pin, that pin cannot be used as a general purpose output. However, the pin can still be read.

TABLE 11-1: PORT AVAILABILITY PER DEVICE

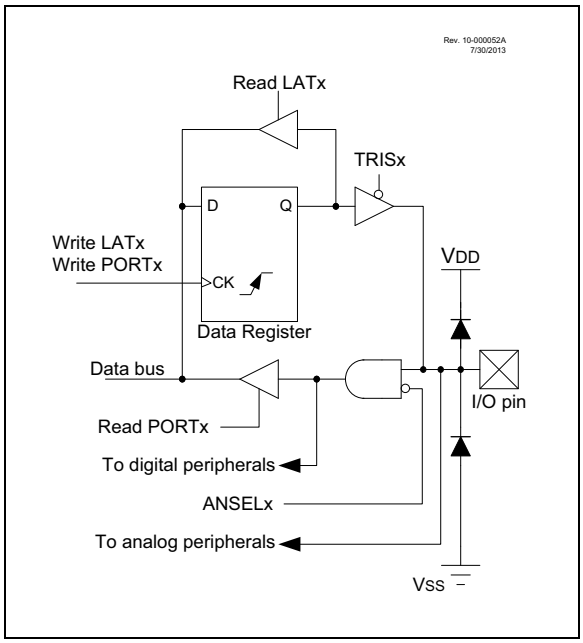
Device	PORTA	PORTB	PORTC
PIC16(L)F1503	•		•

The Data Latch (LATx registers) is useful for read-modify-write operations on the value that the I/O pins are driving.

A write operation to the LATx register has the same effect as a write to the corresponding PORTx register. A read of the LATx register reads of the values held in the I/O PORT latches, while a read of the PORTx register reads the actual I/O pin value.

Ports that support analog inputs have an associated ANSELx register. When an ANSEL bit is set, the digital input buffer associated with that bit is disabled. Disabling the input buffer prevents analog signal levels on the pin between a logic high and low from causing excessive current in the logic input circuitry. A simplified model of a generic I/O port, without the interfaces to other peripherals, is shown in Figure 11-1.

FIGURE 11-1: GENERIC I/O PORT OPERATION



15.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Result formatting

15.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 11.0 "I/O Ports"** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

15.1.2 CHANNEL SELECTION

There are 11 channel selections available:

- AN<7:0> pins
- Temperature Indicator
- FVR_buffer1

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay (T_{ACQ}) is required before starting the next conversion. Refer to **Section 15.2.6 "ADC Conversion Procedure"** for more information.

15.1.3 ADC VOLTAGE REFERENCE

The ADC module uses a positive and a negative voltage reference. The positive reference is labeled ref+ and the negative reference is labeled ref-.

The positive voltage reference (ref+) is selected by the ADPREF bits in the ADCON1 register. The positive voltage reference source can be:

- V_{REF}+ pin
- V_{DD}

The negative voltage reference (ref-) source is:

- V_{SS}

15.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

- F_{OSC}/2
- F_{OSC}/4
- F_{OSC}/8
- F_{OSC}/16
- F_{OSC}/32
- F_{OSC}/64
- FRC (internal RC oscillator)

The time to complete one bit conversion is defined as T_{AD}. One full 10-bit conversion requires 11.5 T_{AD} periods as shown in Figure 15-2.

For correct conversion, the appropriate T_{AD} specification must be met. Refer to the ADC conversion requirements in **Section 28.0 "Electrical Specifications"** for more information. Table 15-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

21.2.2 SPI MODE OPERATION

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits (SSPxCON1<5:0> and SSPxSTAT<7:6>). These control bits allow the following to be specified:

- Master mode (SCKx is the clock output)
- Slave mode (SCKx is the clock input)
- Clock Polarity (Idle state of SCKx)
- Data Input Sample Phase (middle or end of data output time)
- Clock Edge (output data on rising/falling edge of SCKx)
- Clock Rate (Master mode only)
- Slave Select mode (Slave mode only)

To enable the serial port, SSP Enable bit, SSPEN of the SSPxCON1 register, must be set. To reset or reconfigure SPI mode, clear the SSPEN bit, re-initialize the SSPxCONx registers and then set the SSPEN bit. This configures the SDI, SDO, SCK and $\overline{SS}$ pins as serial port pins. For the pins to behave as the serial port function, some must have their data direction bits (in the TRIS register) appropriately programmed as follows:

- SDIx must have corresponding TRIS bit set
- SDOx must have corresponding TRIS bit cleared
- SCKx (Master mode) must have corresponding TRIS bit cleared
- SCKx (Slave mode) must have corresponding TRIS bit set
- $\overline{SSx}$ must have corresponding TRIS bit set

Any serial port function that is not desired may be overridden by programming the corresponding data direction (TRIS) register to the opposite value.

The MSSP consists of a transmit/receive shift register (SSPxSR) and a buffer register (SSPxBUF). The SSPxSR shifts the data in and out of the device, MSb first. The SSPxBUF holds the data that was written to the SSPxSR until the received data is ready. Once the eight bits of data have been received, that byte is moved to the SSPxBUF register. Then, the Buffer Full Detect bit, BF of the SSPxSTAT register, and the interrupt flag bit, SSPxIF, are set. This double-buffering of the received data (SSPxBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPxBUF register during transmission/reception of data will be ignored and the write collision detect bit, WCOL of the SSPxCON1 register, will be set. User software must clear the WCOL bit to allow the following write(s) to the SSPxBUF register to complete successfully.

When the application software is expecting to receive valid data, the SSPxBUF should be read before the next byte of data to transfer is written to the SSPxBUF. The Buffer Full bit, BF of the SSPxSTAT register, indicates when SSPxBUF has been loaded with the received data (transmission is complete). When the SSPxBUF is read, the BF bit is cleared. This data may be irrelevant if the SPI is only a transmitter. Generally, the MSSP interrupt is used to determine when the transmission/reception has completed. If the interrupt method is not going to be used, then software polling can be done to ensure that a write collision does not occur.

The SSPxSR is not directly readable or writable and can only be accessed by addressing the SSPxBUF register. Additionally, the SSPxSTAT register indicates the various Status conditions.

When one device is transmitting a logical one, or letting the line float, and a second device is transmitting a logical zero, or holding the line low, the first device can detect that the line is not a logical one. This detection, when used on the SCLx line, is called clock stretching. Clock stretching gives slave devices a mechanism to control the flow of data. When this detection is used on the SDAx line, it is called arbitration. Arbitration ensures that there is only one master device communicating at any single time.

21.3.1 CLOCK STRETCHING

When a slave device has not completed processing data, it can delay the transfer of more data through the process of clock stretching. An addressed slave device may hold the SCLx clock line low after receiving or sending a bit, indicating that it is not yet ready to continue. The master that is communicating with the slave will attempt to raise the SCLx line in order to transfer the next bit, but will detect that the clock line has not yet been released. Because the SCLx connection is open-drain, the slave has the ability to hold that line low until it is ready to continue communicating.

Clock stretching allows receivers that cannot keep up with a transmitter to control the flow of incoming data.

21.3.2 ARBITRATION

Each master device must monitor the bus for Start and Stop bits. If the device detects that the bus is busy, it cannot begin a new message until the bus returns to an Idle state.

However, two master devices may try to initiate a transmission on or about the same time. When this occurs, the process of arbitration begins. Each transmitter checks the level of the SDAx data line and compares it to the level that it expects to find. The first transmitter to observe that the two levels do not match, loses arbitration, and must stop transmitting on the SDAx line.

For example, if one transmitter holds the SDAx line to a logical one (lets it float) and a second transmitter holds it to a logical zero (pulls it low), the result is that the SDAx line will be low. The first transmitter then observes that the level of the line is different than expected and concludes that another transmitter is communicating.

The first transmitter to notice this difference is the one that loses arbitration and must stop driving the SDAx line. If this transmitter is also a master device, it also must stop driving the SCLx line. It then can monitor the lines for a Stop condition before trying to reissue its transmission. In the meantime, the other device that has not noticed any difference between the expected and actual levels on the SDAx line continues with its original transmission. It can do so without any complications, because so far, the transmission appears exactly as expected with no other transmitter disturbing the message.

Slave Transmit mode can also be arbitrated, when a master addresses multiple slaves, but this is less common.

If two master devices are sending a message to two different slave devices at the address stage, the master sending the lower slave address always wins arbitration. When two master devices send messages to the same slave address, and addresses can sometimes refer to multiple slaves, the arbitration process must continue into the data stage.

Arbitration usually occurs very rarely, but it is a necessary process for proper multi-master support.

22.1.9 SETUP FOR PWM OPERATION USING PWMx PINS

The following steps should be taken when configuring the module for PWM operation using the PWMx pins:

1. Disable the PWMx pin output driver(s) by setting the associated TRIS bit(s).
2. Clear the PWMxCON register.
3. Load the PR2 register with the PWM period value.
4. Clear the PWMxDCH register and bits <7:6> of the PWMxDCL register.
5. Configure and start Timer2:
   - Clear the TMR2IF interrupt flag bit of the PIR1 register. See note below.
   - Configure the T2CKPS bits of the T2CON register with the Timer2 prescale value.
   - Enable Timer2 by setting the TMR2ON bit of the T2CON register.
6. Enable PWM output pin and wait until Timer2 overflows, TMR2IF bit of the PIR1 register is set. See note below.
7. Enable the PWMx pin output driver(s) by clearing the associated TRIS bit(s) and setting the PWMxOE bit of the PWMxCON register.
8. Configure the PWM module by loading the PWMxCON register with the appropriate values.

Note 1: In order to send a complete duty cycle and period on the first PWM output, the above steps must be followed in the order given. If it is not critical to start with a complete PWM signal, then move Step 8 to replace Step 4.

2: For operation with other peripherals only, disable PWMx pin outputs.

REGISTER 23-5: CLCxGLS0: GATE 1 LOGIC SELECT REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LCxG1D4T	LCxG1D4N	LCxG1D3T	LCxG1D3N	LCxG1D2T	LCxG1D2N	LCxG1D1T	LCxG1D1N
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **LCxG1D4T:** Gate 1 Data 4 True (non-inverted) bit
1 = lcxd4T is gated into lcxg1
0 = lcxd4T is not gated into lcxg1

bit 6 **LCxG1D4N:** Gate 1 Data 4 Negated (inverted) bit
1 = lcxd4N is gated into lcxg1
0 = lcxd4N is not gated into lcxg1

bit 5 **LCxG1D3T:** Gate 1 Data 3 True (non-inverted) bit
1 = lcxd3T is gated into lcxg1
0 = lcxd3T is not gated into lcxg1

bit 4 **LCxG1D3N:** Gate 1 Data 3 Negated (inverted) bit
1 = lcxd3N is gated into lcxg1
0 = lcxd3N is not gated into lcxg1

bit 3 **LCxG1D2T:** Gate 1 Data 2 True (non-inverted) bit
1 = lcxd2T is gated into lcxg1
0 = lcxd2T is not gated into lcxg1

bit 2 **LCxG1D2N:** Gate 1 Data 2 Negated (inverted) bit
1 = lcxd2N is gated into lcxg1
0 = lcxd2N is not gated into lcxg1

bit 1 **LCxG1D1T:** Gate 1 Data 1 True (non-inverted) bit
1 = lcxd1T is gated into lcxg1
0 = lcxd1T is not gated into lcxg1

bit 0 **LCxG1D1N:** Gate 1 Data 1 Negated (inverted) bit
1 = lcxd1N is gated into lcxg1
0 = lcxd1N is not gated into lcxg1

REGISTER 23-7: CLCxGLS2: GATE 3 LOGIC SELECT REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LCxG3D4T	LCxG3D4N	LCxG3D3T	LCxG3D3N	LCxG3D2T	LCxG3D2N	LCxG3D1T	LCxG3D1N
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **LCxG3D4T:** Gate 3 Data 4 True (non-inverted) bit
1 = lcxd4T is gated into lcxg3
0 = lcxd4T is not gated into lcxg3

bit 6 **LCxG3D4N:** Gate 3 Data 4 Negated (inverted) bit
1 = lcxd4N is gated into lcxg3
0 = lcxd4N is not gated into lcxg3

bit 5 **LCxG3D3T:** Gate 3 Data 3 True (non-inverted) bit
1 = lcxd3T is gated into lcxg3
0 = lcxd3T is not gated into lcxg3

bit 4 **LCxG3D3N:** Gate 3 Data 3 Negated (inverted) bit
1 = lcxd3N is gated into lcxg3
0 = lcxd3N is not gated into lcxg3

bit 3 **LCxG3D2T:** Gate 3 Data 2 True (non-inverted) bit
1 = lcxd2T is gated into lcxg3
0 = lcxd2T is not gated into lcxg3

bit 2 **LCxG3D2N:** Gate 3 Data 2 Negated (inverted) bit
1 = lcxd2N is gated into lcxg3
0 = lcxd2N is not gated into lcxg3

bit 1 **LCxG3D1T:** Gate 3 Data 1 True (non-inverted) bit
1 = lcxd1T is gated into lcxg3
0 = lcxd1T is not gated into lcxg3

bit 0 **LCxG3D1N:** Gate 3 Data 1 Negated (inverted) bit
1 = lcxd1N is gated into lcxg3
0 = lcxd1N is not gated into lcxg3

REGISTER 25-4: CWGxDBR: COMPLEMENTARY WAVEFORM GENERATOR (CWGx) RISING DEAD-BAND COUNT REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	CWG**x**DBR<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **CWGxDBR<5:0>:** Complementary Waveform Generator (CWGx) Rising Counts

11 1111 = 63-64 counts of dead band
11 1110 = 62-63 counts of dead band

•
•
•

00 0010 = 2-3 counts of dead band
00 0001 = 1-2 counts of dead band
00 0000 = 0 counts of dead band

REGISTER 25-5: CWGxDBF: COMPLEMENTARY WAVEFORM GENERATOR (CWGx) FALLING DEAD-BAND COUNT REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	CWGxDBF<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **CWGxDBF<5:0>:** Complementary Waveform Generator (CWGx) Falling Counts

11 1111 = 63-64 counts of dead band
11 1110 = 62-63 counts of dead band

•
•
•

00 0010 = 2-3 counts of dead band
00 0001 = 1-2 counts of dead band
00 0000 = 0 counts of dead band. Dead-band generation is bypassed.

28.0 ELECTRICAL SPECIFICATIONS

28.1 Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on pins with respect to V_{SS}
- on V_{DD} pin
  - PIC16F1503 ..... -0.3V to +6.5V
  - PIC16LF1503 ..... -0.3V to +4.0V
- on $\overline{MCLR}$ pin ..... -0.3V to +9.0V
- on all other pins ..... -0.3V to (V_{DD} + 0.3V)

Maximum current
- on V_{SS} pin(1)
  - -40°C ≤ T_A ≤ +85°C ..... 250 mA
  - +85°C ≤ T_A ≤ +125°C ..... 85 mA
- on V_{DD} pin(1)
  - -40°C ≤ T_A ≤ +85°C ..... 250 mA
  - +85°C ≤ T_A ≤ +125°C ..... 85 mA
- Sunk by any standard I/O pin ..... 50 mA
- Sourced by any standard I/O pin ..... 50 mA

Clamp current, I_K (V_{PIN} < 0 or V_{PIN} > V_{DD}) ..... ±20 mA
Total power dissipation(2) ..... 800 mW

Note 1: Maximum current rating requires even load distribution across I/O pins. Maximum current rating may be limited by the device package power dissipation characterizations, see Table 28-6 to calculate device specifications.

2: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

TABLE 28-3: POWER-DOWN CURRENTS (I_{PD})(1,2) (CONTINUED)

PIC16LF1503		Operating Conditions: (unless otherwise stated) Low-Power Sleep Mode						
PIC16F1503		Low-Power Sleep Mode, VREGPM = 1						
Param. No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							V_{DD}	Note
D026		—	0.11	1.5	9.0	µA	1.8	ADC Current **(Note 3)**, No conversion in progress
		—	0.12	2.7	12	µA	3.0	
D026		—	0.30	4.0	11	µA	2.3	ADC Current **(Note 3)**, No conversion in progress
		—	0.35	5.0	13	µA	3.0	
		—	0.45	8.0	16	µA	5.0	
D026A*		—	250	—	—	µA	1.8	ADC Current **(Note 3)**, Conversion in progress
		—	250	—	—	µA	3.0	
D026A*		—	280	—	—	µA	2.3	ADC Current **(Note 3)**, Conversion in progress
		—	280	—	—	µA	3.0	
		—	280	—	—	µA	5.0	
D027		—	7	22	25	µA	1.8	Comparator, CxSP = 0
		—	8	23	27	µA	3.0	
D027		—	17	35	37	µA	2.3	Comparator, CxSP = 0
		—	18	37	38	µA	3.0	
		—	19	38	40	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral Δ current can be determined by subtracting the base I_{PD} current from this limit. Max. values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{SS}.

3: ADC clock source is FRC.

FIGURE 29-3: IDD, EXTERNAL CLOCK (ECL), LOW-POWER MODE, FOSC = 500 kHz, PIC16LF1503 ONLY

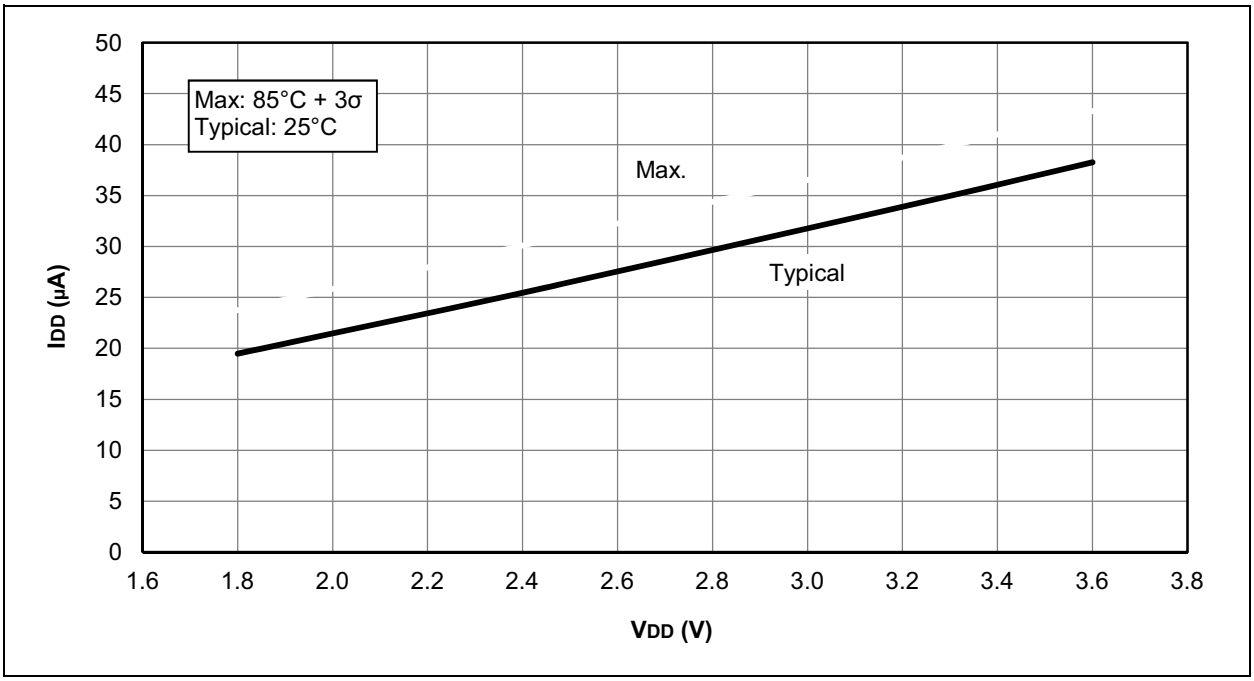


FIGURE 29-4: IDD, EXTERNAL CLOCK (ECL), LOW-POWER MODE, FOSC = 500 kHz, PIC16F1503 ONLY

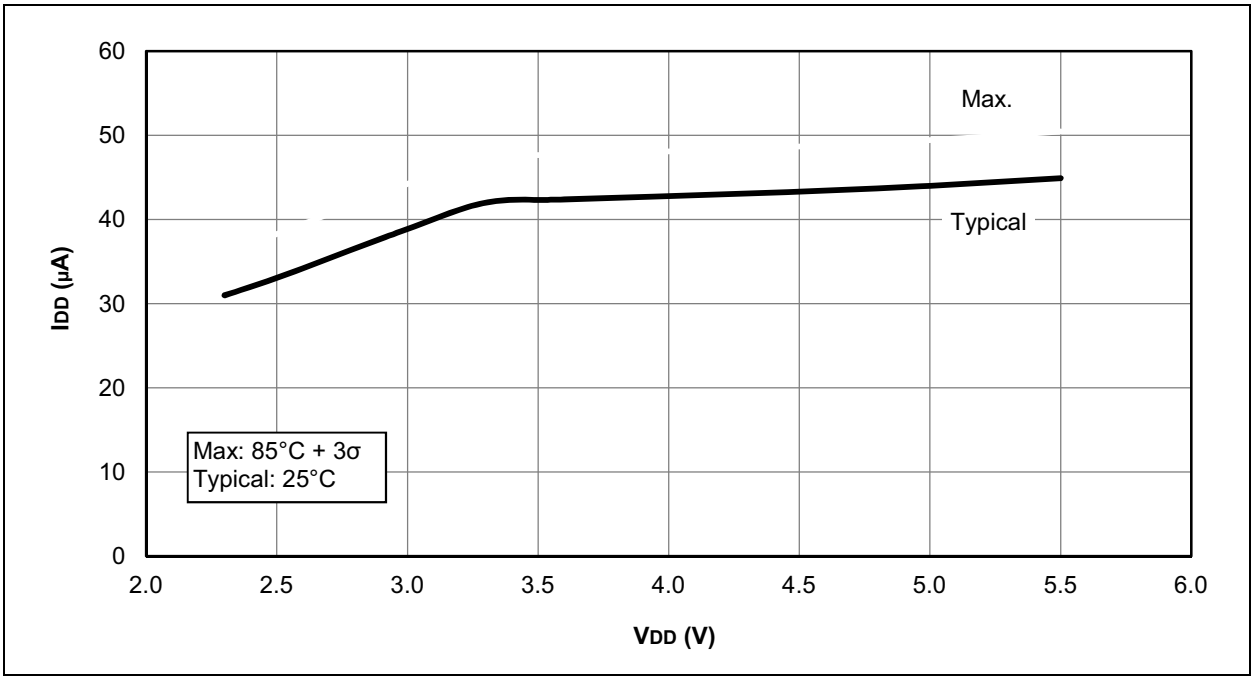


FIGURE 29-31: IPD, COMPARATOR, LOW-POWER MODE (CxSP = 0), PIC16LF1503 ONLY

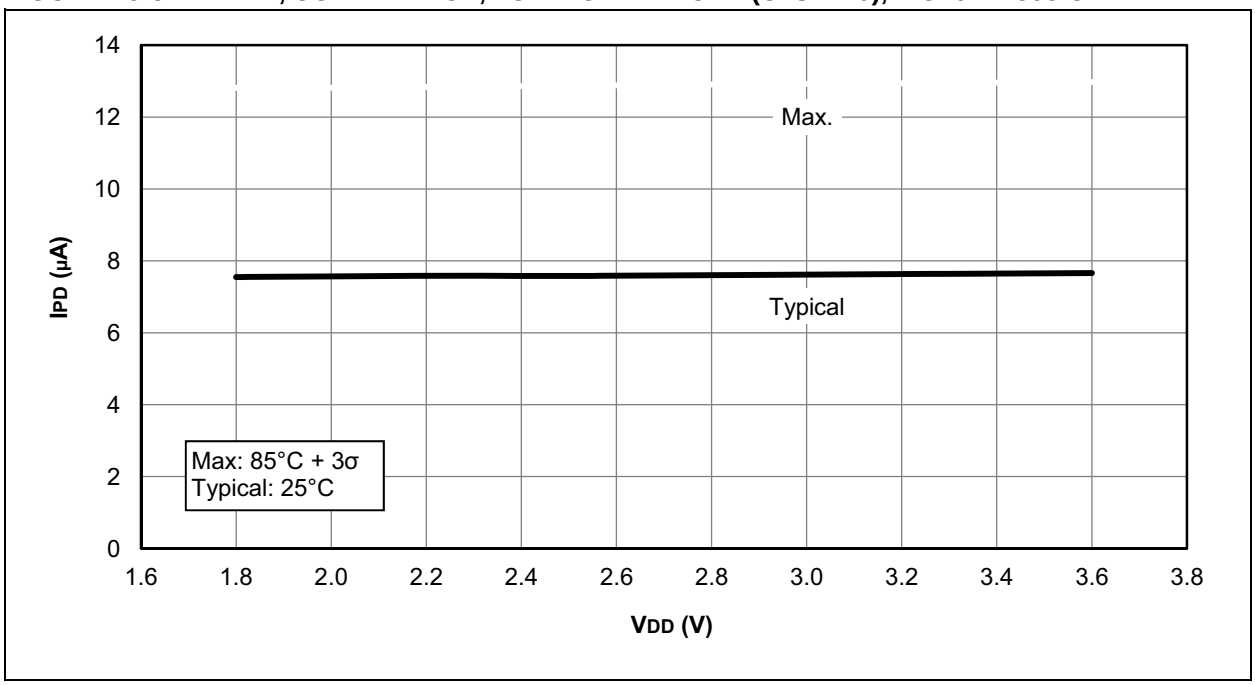


FIGURE 29-32: IPD, COMPARATOR, LOW-POWER MODE (CxSP = 0), PIC16F1503 ONLY

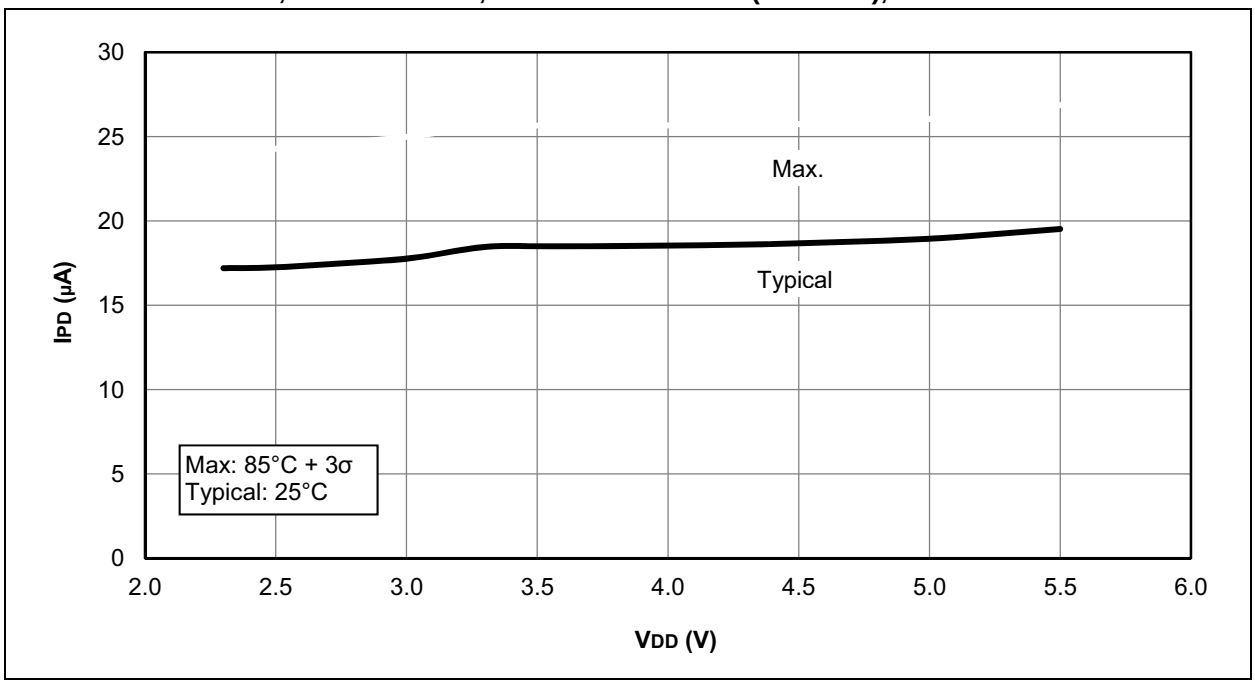


FIGURE 29-43: BROWN-OUT RESET VOLTAGE, BORV = 1, PIC16LF1503 ONLY

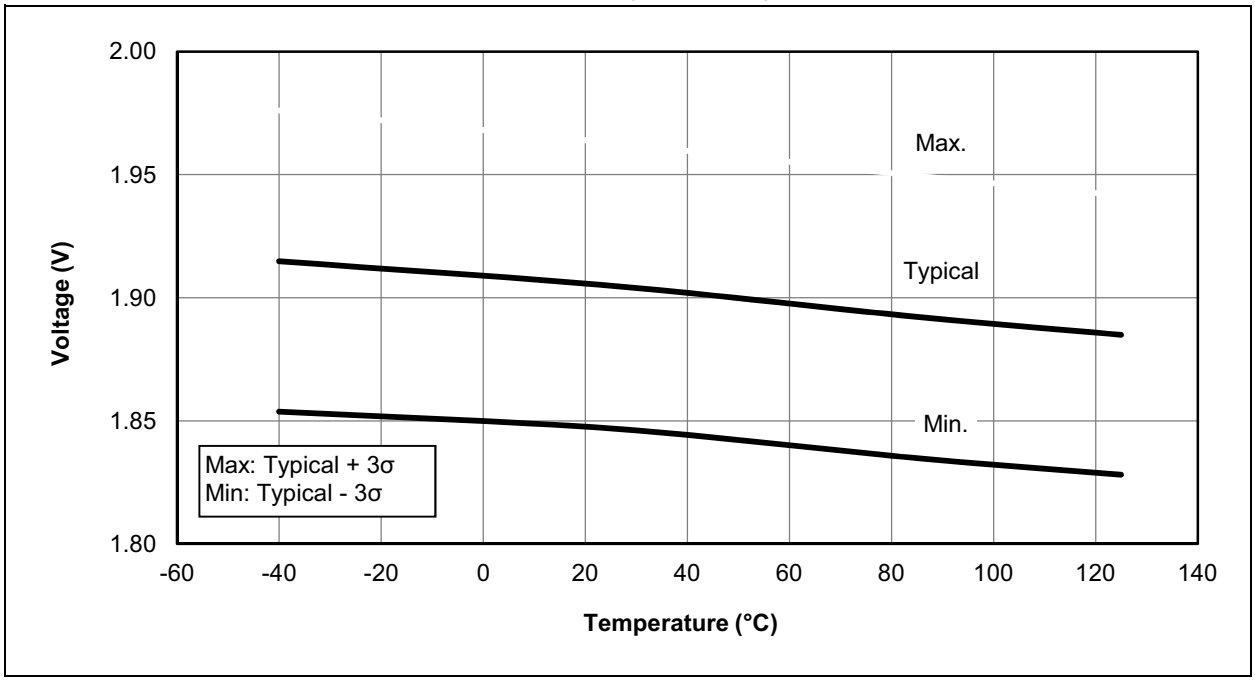
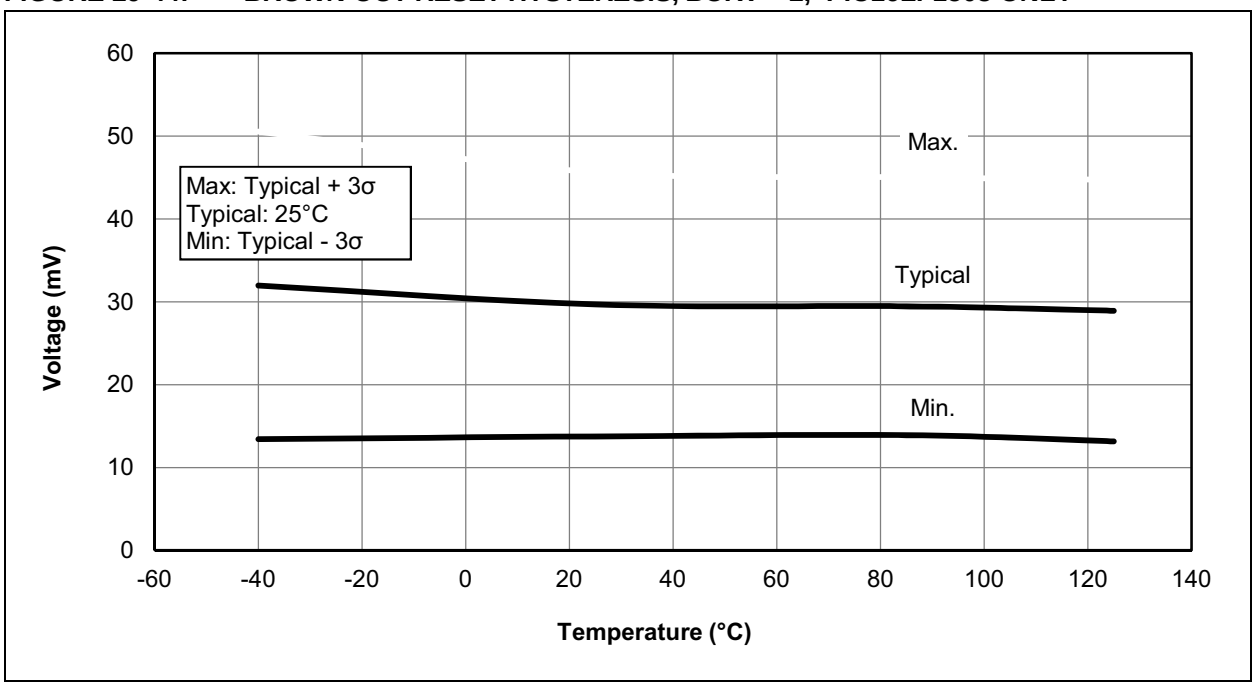


FIGURE 29-44: BROWN-OUT RESET HYSTERESIS, BORV = 1, PIC16LF1503 ONLY



30.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

30.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

30.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

30.9 PICkit 3 In-Circuit Debugger/ Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

30.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

31.1 Package Marking Information (Continued)

16-Lead QFN (3x3x0.9 mm)

Example

16-Lead UQFN (3x3x0.5 mm)

Example

TABLE 31-1: 16-LEAD 3x3x0.9 QFN (MG) TOP MARKING

Part Number	Marking
PIC16F1503(T)-I/MG	MGA
PIC16F1503(T)-E/MG	MGB
PIC16LF1503(T)-I/MG	MGC
PIC16LF1503(T)-E/MG	MGD

TABLE 31-2: 16-LEAD 3x3x0.5 UQFN (MV) TOP MARKING

Part Number	Marking
PIC16F1503(T)-I/NL	AAB
PIC16F1503(T)-E/NL	AAA
PIC16LF1503(T)-I/NL	AAD
PIC16LF1503(T)-E/NL	AAC

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